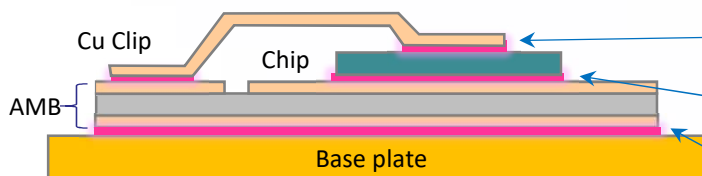


Pressure Sintering

Features

- Both pressure and pressure-less available
- Excellent bonding to Cu
- Small to large area bonding
- RoHS Compliance & High performance



Clip Attach (Pressure/Pressureless)

Die Attach (Pressure/Pressureless)

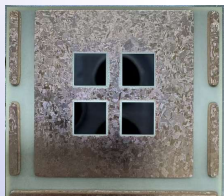
Substrate Attach (Pressure/Pressureless)

Sintering for SiC die

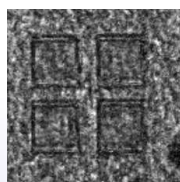
TS-985A-G6HD

Bonding to **Cu AMB**

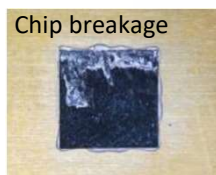
5mm x 5mm SiC (Ag BSM) / AMB (Bare Cu)



250°C, 20MPa, 2min



Thru scan



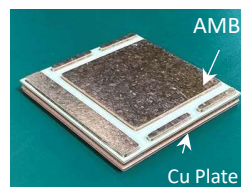
Chip breakage

DSS >70MPa

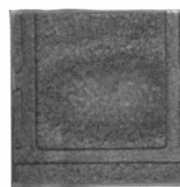
TS-9854

Bonding to **Cu Plate**

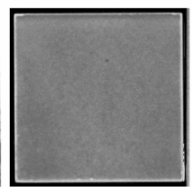
35mm x 35mm AMB(Bare Cu)/ Cu plate (1.5mmt)



250°C, 20MPa, 2min



Thru scan



C scan

	TS-985A-G6HD	TS-9854 / H
Category	Ag Sintering with Pressure	Hybrid Sintering with Pressure
Process	Dispensing/ Printing	Dispensing/ Printing
Viscosity	35 Pa.s	25Pa.s / 40Pa.s
Die Shear Strength at RT	>70 MPa	>70 MPa
Elastic Modulus at RT	(23,000 MPa)*	(15,000 MPa)*
Thermal Conductivity	>300 W/m.K	>150 W/m.K
Metallization	Ag, Au, Cu	Ag, Au, Cu
Bond area	~10mm x 10mm	~50mm x 50mm

*Measurement value with non pressured condition



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